

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC7541ABSW#PBF

(Engineering Calculation)

S0C WIDE

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TOTAL MASS (g): 0.510686

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002923	1000000	5527.86230469	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.161470	975000	316182.71875	
		Iron (Fe)	7439-89-6	0.003975	24000	7783.6532031	
		Phosphorus (P)	7723-14-0	0.000050	300	97.9075775146	
		Zinc (Zn)	7440-66-6	0.000116	700	227.145584106	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-95-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		<b>Lead Frame Total:</b>			<b>0.165611</b>	<b>1000000</b>	<b>324291.4378</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0
Exter. Plating Sn	7440-31-5			0.005671	1000000	11104.1542969	
<b>External Plating Total:</b>					<b>0.005671</b>	<b>1000000</b>	<b>11104.1542969</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0	
Inter. Plating Ag	7440-22-4			0.001325	1000000	2594.55078125	
<b>Internal Plating Total:</b>					<b>0.001325</b>	<b>1000000</b>	<b>2594.55078125</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000865	750000	1693.80114746	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000288	250000	563.947692871	
		<b>Die Attach Total:</b>			<b>0.001153</b>	<b>1000000</b>	<b>2257.74902344</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.045041	135000
Bromine (Br)	40079-93-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.286939	860000	561870.0625	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000000	0	0	
Carbon Black (C)	1333-86-4			0.001668	5000	3266.19702148	
<b>Encapsulation Total:</b>					<b>0.333650</b>	<b>1000000</b>	<b>653337.3125</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000453	1000000	887.042663574	

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